UNITED STATES
SECURITIES AND EXCHANGE COMMISSION
Washington, D.C. 20549

FORM 8-K

CURRENT REPORT
Pursuant to Section 13 or 15(d) of the Securities Exchange Act of 1934

Date of Report (Date of earliest event reported): September 28, 2011

TTM TECHNOLOGIES, INC.

(Exact name of registrant as specified in its charter)

DELAWARE	**0-31285**	**91-1033443**
(State or other Jurisdiction of Incorporation)	(Commission File Number)	(IRS Employer Identification No.)

2630 SOUTH HARBOR BOULEVARD SANTA ANA, CALIFORNIA	**92704**
(Address of Principal Executive Offices)	(Zip Code)

Registrant's telephone number, including area code: **(714) 327-3000**

(Former name or former address if changed since last report.)

Check the appropriate box below if the Form 8-K filing is intended to simultaneously satisfy the filing obligation of the registrant under any of the following provisions:

☐ Written communications pursuant to Rule 425 under the Securities Act (17 CFR 230.425)

☐ Soliciting material pursuant to Rule 14a-12 under the Exchange Act (17 CFR 240.14a-12)

☐ Pre-commencement communications pursuant to Rule 14d-2(b) under the Exchange Act (17 CFR 240.14d-2(b))

☐ Pre-commencement communications pursuant to Rule 13e-4(c) under the Exchange Act (17 CFR 240.13e-4(c))

Item 7.01. Regulation FD Disclosure.

We are filing this Current Report on Form 8-K in connection with the disclosure of textual information from a slide show presentation given at the TTM Technologies 2011 Analyst Day on September 28, 2011. A copy of this slide show presentation is being furnished as Exhibit 99.1 to this Current Report on Form 8-K.

The information in this Current Report (including the exhibit) is furnished pursuant to Item 7.01 and shall not be deemed to be "filed" for the purpose of Section 18 of the Securities Exchange Act of 1934, as amended, or otherwise subject to the liabilities of that section. This Current Report will not be deemed an admission as to the materiality of any information in this Current Report that is required to be disclosed solely by Regulation FD.

We do not have, and expressly disclaim, any obligation to release publicly any updates or any changes in our expectations or any change in events, conditions, or circumstances on which any forward-looking statement is based.

The information included with this Current Report (including the exhibit) will be available at our website located at www.ttmtech.com, although we reserve the right to discontinue that availability at any time.

The information in this Report includes references to "Adjusted EBITDA." Adjusted EBITDA is defined as earnings before interest expense, income taxes, depreciation, amortization and asset impairment. We present adjusted EBITDA to enhance the understanding of our operating results. Adjusted EBITDA is a key measure we use to evaluate our operations. In addition, we provide our adjusted EBITDA because we believe that investors and securities analysts will find adjusted EBITDA to be a useful measure for evaluating our operating performance and comparing our operating performance with that of similar companies that have different capital structures and for evaluating our ability to meet our future debt service, capital expenditures and working capital requirements. However, adjusted EBITDA should not be considered as an alternative to cash flows from operating activities as a measure of liquidity or as an alternative to net income as a measure of operating results in accordance with accounting principles generally accepted in the United States of America.

Item 9.01. Financial Statements and Exhibits.

(d) *Exhibits*.

99.1 Slides presented at the TTM Technologies 2011 Analyst Day on September 28, 2011.

SIGNATURE

Pursuant to the requirements of the Securities Exchange Act of 1934, the registrant has duly caused this report to be signed on its behalf by the undersigned hereunto duly authorized.

TTM TECHNOLOGIES, INC.

Date: September 28, 2011

By: /s/ Steven W. Richards
Steven W. Richards
Chief Financial Officer

Exhibit 99.1

Company and Industry Overview

Global Presence | Local Knowledge

Kent Alder

September 28, 2011

Safe Harbor

During the course of this presentation, the company will make forward-looking statements subject to known and unknown risks and uncertainties that could cause actual results to differ materially from those expressed or implied by such statements. Such risks and uncertainties include, but are not limited to, fluctuations in quarterly and annual operating results, the volatility and cyclicality of various industries that the company serves and other risks described in TTM's most recent SEC filings. The company assumes no obligation to update the information provided in this presentation.

The company also will present non-GAAP financial information in this presentation. For a reconciliation of TTM's non-GAAP financial information to the equivalent measures under GAAP, please refer to the company's press release, which was filed with the SEC and which is posted on TTM's website.

Presenting Today

Kenton K. Alder
President & CEO

31 years of industry experience
Prior companies: Tyco Electronics, ElectroStar

Canice T.K. Chung
CEO, Asia Pacific Region

21 years of industry experience
Prior companies: Elec & Eltek, Fairchild Semiconductor

Steven W. Richards
EVP, Chief Financial Officer

11 years of industry experience
Prior companies: Atlantic Richfield

Douglas L. Soder
EVP

28 years of industry experience
Prior companies: Tyco Electronics, Amp Inc.

Shane Whiteside
EVP, Chief Operating Officer

18 years of industry experience
Prior companies: Power Circuits, Technica USA

Global Leader in PCB Manufacturing

- Top 5 global PCB manufacturer - $1.4 billion in revenue*
- 15 specialized factories located in U.S. and China
- Over 17,000 employees worldwide
- Focused on advanced technology products
- Total customer solution: prototype through production
- Technology development coordinated with customers' needs
- Diversified end markets with broad customer base

* Pro forma 2010

Specialized Facilities Provide Optimal Growth

Integrated manufacturing platform enables TTM to execute a global facility specialization strategy

Aerospace/Defense
1. Stafford, CT
2. Santa Clara, CA
3. San Diego, CA

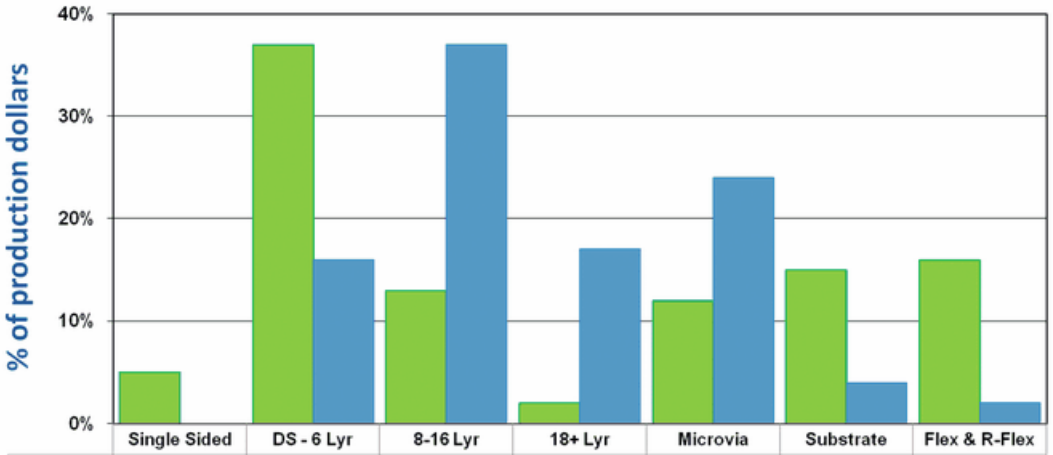
High Tech/Quick-Turn/High Mix
4. Chippewa Falls, WI
5. Santa Ana, CA
6. Logan, UT
7. Hong Kong – OPCM

Focused Assembly
8. Shanghai, China
9. Stafford Springs, CT

Volume Production
10. Dongguan – DMC
11. Dongguan – SYE
12. Guangzhou – GME
13. Shanghai – SME
14. Suzhou – MAS

Substrate
15. Shanghai - SMST

2010 World PCB Production by Product Type

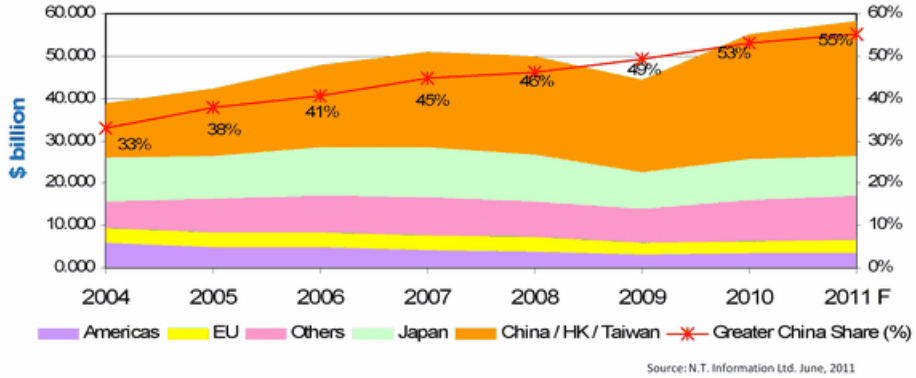


	Single Sided	DS - 6 Lyr	8-16 Lyr	18+ Lyr	Microvia	Substrate	Flex & R-Flex
World	5%	37%	13%	2%	12%	15%	16%
TTM Total	0%	16%	37%	17%	24%	4%	2%

Source: Prismark Partners, August 2011

TTM is focused on advanced technology

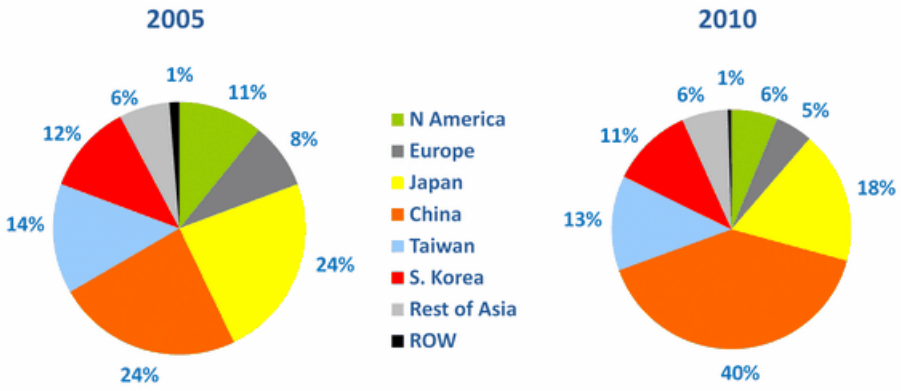
World PCB Outlook



Source: N.T. Information Ltd. June, 2011

- The worldwide PCB market grew 24% in 2010 following the global slowdown in 2008-2009
- 55% of world PCB production will be generated from the Greater China region in 2011
- PCB production in the Americas has declined over time but remains significant to TTM

Historical PCB Production by Region



$ in thousands

Year / Region	N. America	Europe	Japan	China	Taiwan	S. Korea	Rest of Asia	ROW	Total
2005	4,583	3,605	9,995	10,060	5,980	4,890	2,750	539	42,402
2010	3,330	2,801	9,895	22,185	7,076	6,087	3,437	271	55,082
% change	-27%	-22%	-1%	121%	18%	24%	25%	-50%	30%

Expectations are for continued growth in China

Source: N.T. Information Ltd. Sept 2007, June 2011

Growth of World Top 20 PCB Makers

	PCB Maker ($ millions)	2005
1	Ibiden	1,444
2	Nippon Mektron	1,135
3	CMK	1,084
4	Shinko Electric	967
5	Samsung	957
6	Unimicron	930
7	Nanya PCB	839
8	Youg Poong Group	700
9	Kingboard PCB	694
10	Daeduck	654
11	Fujikura	645
12	Multek	620
13	Compeq	606
14	Hitachi Chemical	586
15	**TTM Technologies**	**508**
16	LG Electronics	488
17	Tripod	466
18	Viasystems	465
19	Sanmina-SCI	460
20	Wus	454
	Top 20	14,702
	% of World	35%

	PCB Maker ($millions)	2010
1	Unimicron	2,179
2	Ibiden	2,110
3	Nippon Mektron	2,106
4	Tripod	1,370
5	**TTM Technologies**	**1,366**
6	Samsung	1,282
7	Nanya PCB	1,158
8	Foxconn	1,150
9	HannStar	1,148
10	Kingboard PCB	1,122
11	Shinko Denki	1,003
12	Young Poong Group	978
13	CMK	968
14	Multek	910
15	Meiko	**817**
16	Viasystems	806
17	Daeduck	800
18	Mflex	791
19	Fujikura	778
20	Compeq	738
	Top 20	23,580
	% of World	43%

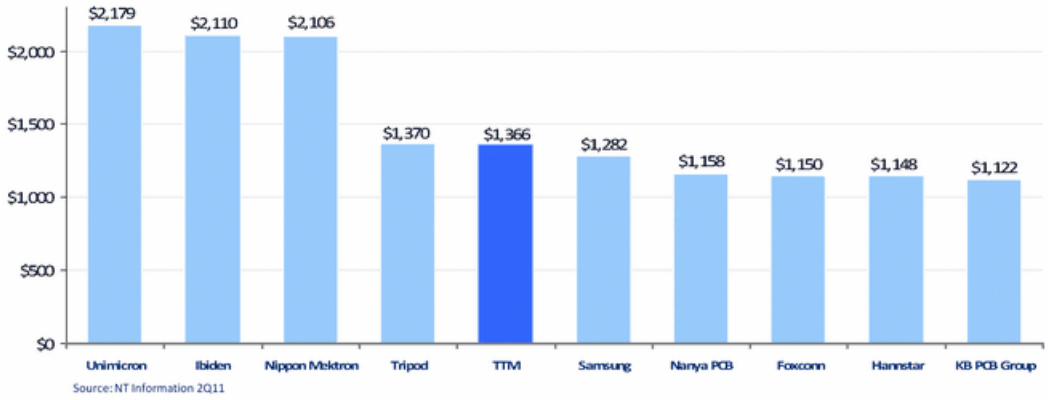
Source: NT Information

Current Global Ranking

Top 10 World PCB Makers 2010

($ in Millions)

Represents approximately 27% of 2010 total world PCB output



Source: NT Information 2Q11

Leading Position in Growing Market Segments

- Core supplier to wide range of high-end networking products addressing increasing bandwidth demands
- Key supplier in rapidly growing touch screen tablet market
- Expanding position in smartphones
- Leadership position in strategic North America Aerospace & Defense industry

World PCB Company Ranking 2010

Top 10 World PCB Makers ($ millions)

Rank	Company	Revenue est.	Rank	Company	Revenue est.
1	Unimicron	$2,179	6	Samsung	$1,282
2	Ibiden	$2,110	7	Nanya PCB	$1,158
3	Nippon Mektron	$2,106	8	Foxconn	$1,150
4	Tripod	$1,370	9	Hannstar + GBM Group	$1,148
5	**TTM Technologies ***	**$1,366**	**10**	KB PCB Group	$1,122

NT Information August 2011

Represents approximately 27% of total world PCB output

Top 5 Americas PCB Makers ($ millions)

Rank	Company	Revenue est.
1	**TTM Technologies×**	**$524**
2	DDI (includes Coretec)	$268
3	Viasystems	$148
4	Sanmina-SCI	$135
5	Endicott Interconnect	$95

NT Information August 2011

Represents approximately 36% of total Americas PCB output

Top 5 China PCB Makers ($millions)

Rank	Company	Revenue est.
1	Tripod	$1,208
2	Foxconn	$1,150
3	Kingboard	$1,122
4	Hannstar	$1,078
5	**TTM Technologies**	**$792**

NT Information June 2011

Represents approximately 24% of total China PCB output

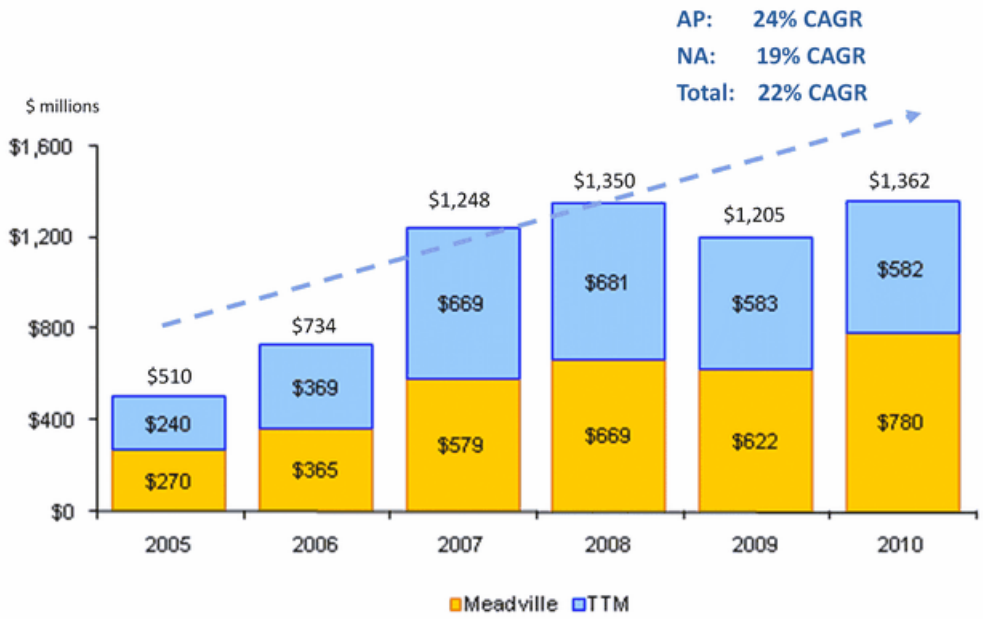
*** Includes Meadville pro forma**

×Excludes Shanghai backplane assembly sales

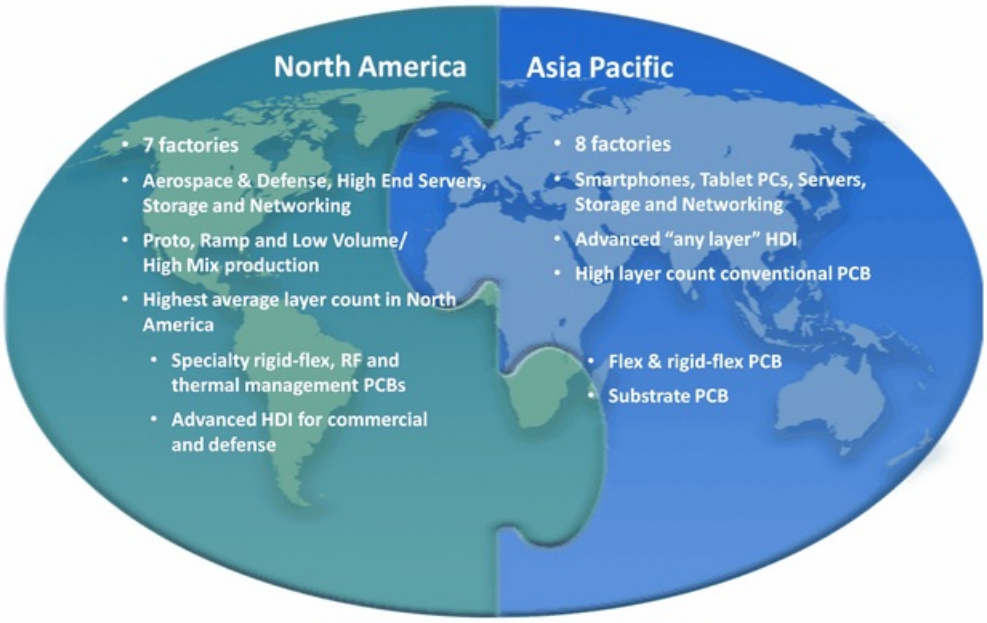
Current Market Dynamics

- Global Market Environment is Challenged
  - Focus on right areas of growth and re-invest in capacity and technology
- PCB Industry
  - Asia
    - Continued growth forecast
    - Smaller competitors unable to invest in technology and overcome increasing costs
    - Large makers continue to get bigger
  - North America & Europe
    - Low growth environment
    - HDI technology expands to other end markets
    - Focus on efficiency supports growth in some areas
      - DoD budgetary priorities favor technology
      - Modernization of medical industry drives IT spending
      - Enterprises evaluating more cost efficient solutions for storage and computing
    - Smaller competitors fall behind in cap-ex spending

Historical Pro Forma Sales



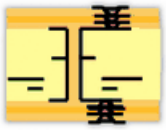
Global Strength



Combined Strength, Total Solution

Positioned for Revolutionary Growth

Advanced PCB and Semiconductor Technology



Proliferation of "Converged Mobile Devices"

TTM Technologies

Demand for Advanced Printed Circuit Board Technology

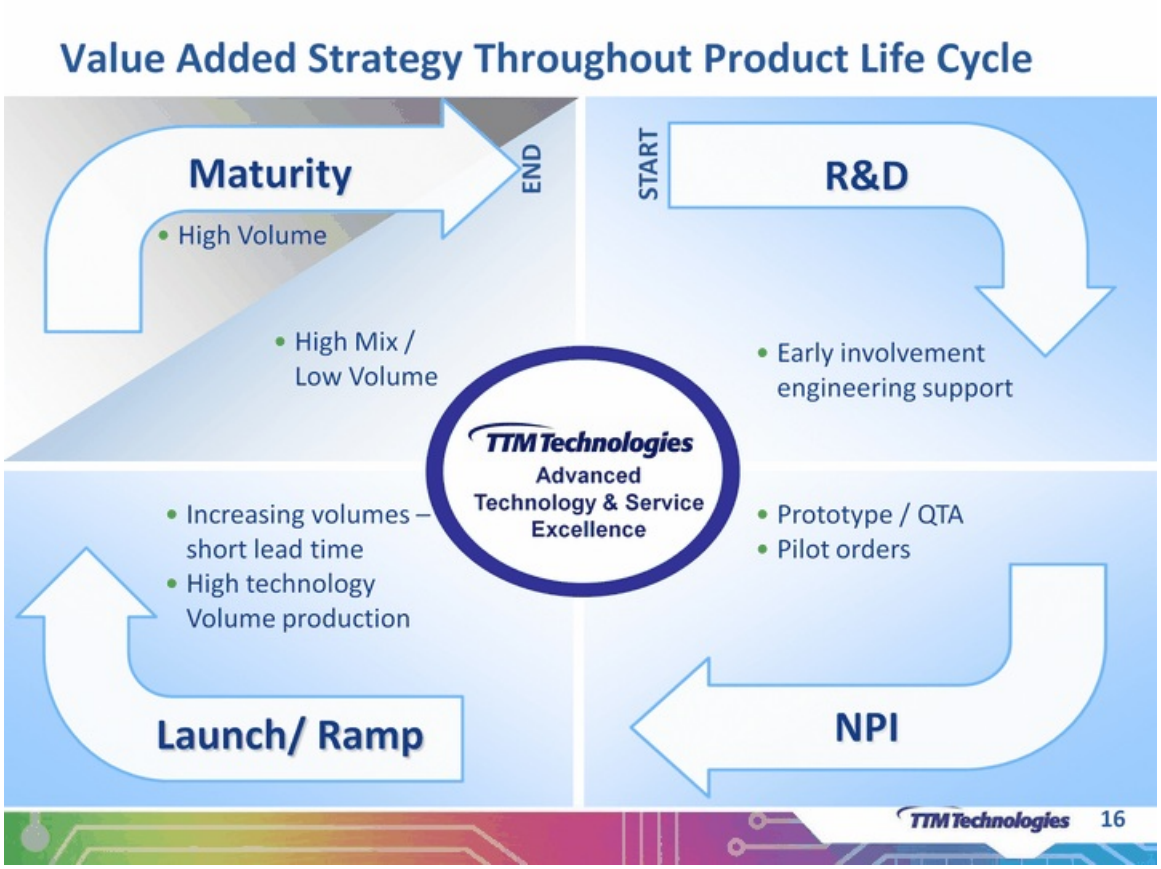
Expansion in Communication, Networking & Storage Infrastructure

Explosion of Network Applications & Cloud Computing

facebook. NETFLIX Google hulu

Consumer

Business


Value Added Strategy Throughout Product Life Cycle
Maturity
END
• High Volume
• High Mix / Low Volume
START
R&D
• Early involvement engineering support
TTM Technologies
Advanced Technology & Service Excellence
• Increasing volumes – short lead time
• High technology Volume production
Launch/ Ramp
• Prototype / QTA
• Pilot orders
NPI
TTM Technologies
16

Key Initiatives

- **AP - Growth Strategy**
  - Focus on smartphone, touch-pad tablets and other hand-held devices by expanding further in advanced HDI flex and rigid-flex
  - Continue to grow higher conventional technology capabilities for networking infrastructure
  - Leverage niche position in substrate
  - Grow organically
- **NA - Growth Strategy**
  - Continued focus in advanced technology, HMLV and QTA
  - Expand HDI capacity for North America requirements
  - Leverage A&D market leadership
- Grow business by servicing customers globally
- Manage balance sheet for growth and risk

Summary - Competitive Advantages

- Continue to invest in advanced HDI technology
- Leverage global customer service & footprint
- Strong balance sheet management
- Grow organically / acquisition
- Diversification of end markets, geographies and product mix reduces risk
- Experienced management team

THANK YOU!

Sales Force and Markets

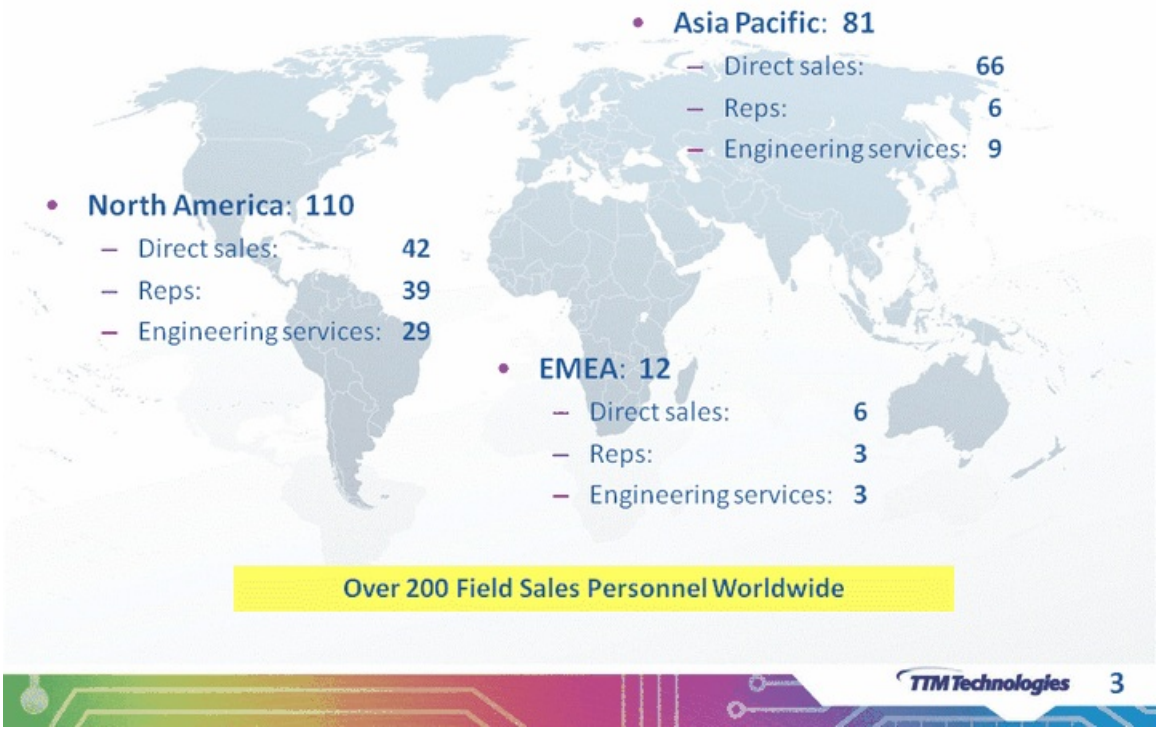
Global Presence | Local Knowledge

Douglas L. Soder
September 28, 2011

Overview

- Sales force
- Customers
- End markets
- Business development cycles

Large Global Sales Force

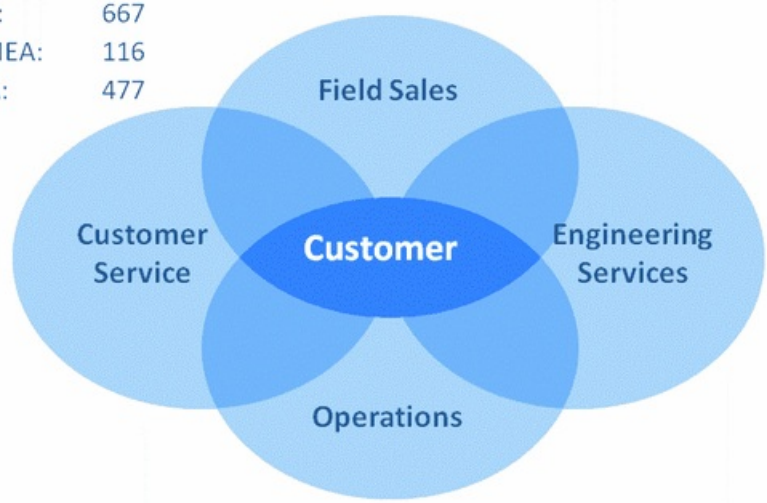


- **Asia Pacific: 81**
  - Direct sales: 66
  - Reps: 6
  - Engineering services: 9
- **North America: 110**
  - Direct sales: 42
  - Reps: 39
  - Engineering services: 29
- **EMEA: 12**
  - Direct sales: 6
  - Reps: 3
  - Engineering services: 3

Over 200 Field Sales Personnel Worldwide

Customer Focused Business Model

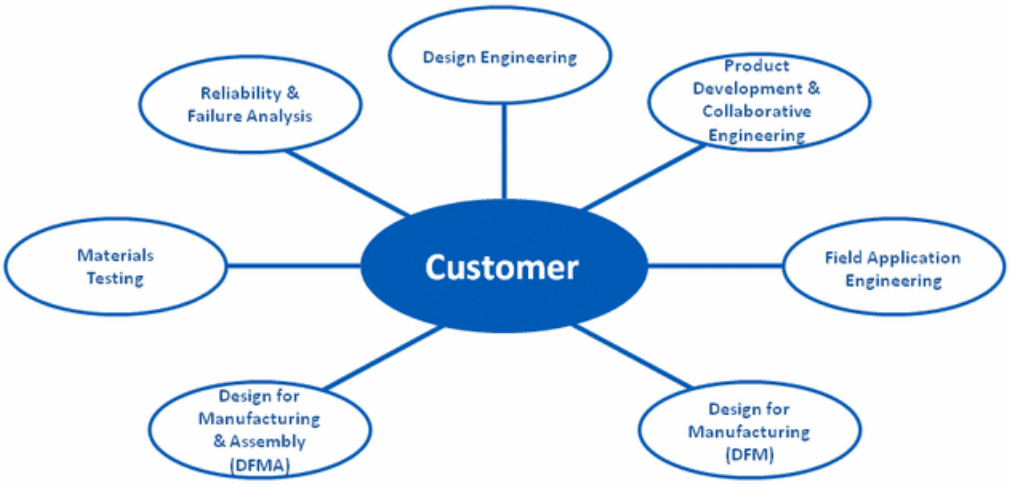
- Total Active OEM Customers: 1,260
  - AP: 667
  - EMEA: 116
  - NA: 477
- Total Active EMS Customers: 256



Over 1,500 active customers

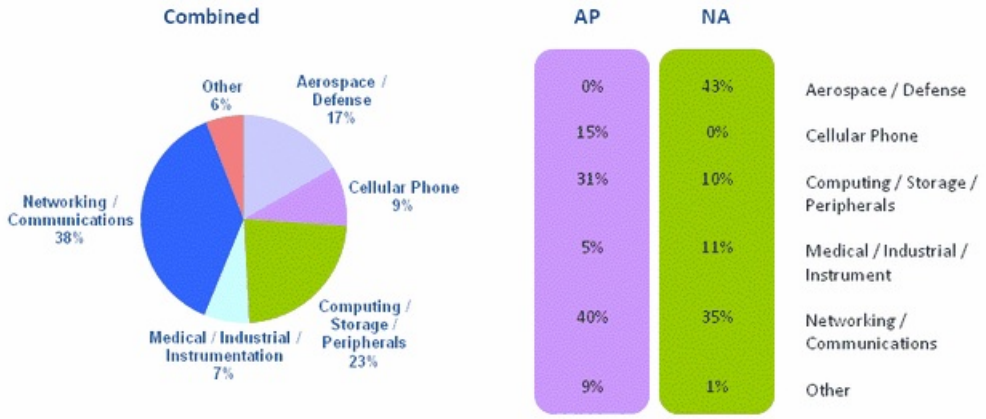
Based on 2Q 2011 trailing 12 months

Engineering Services



Supporting strategic technology engagement with customers & creating competitive advantage

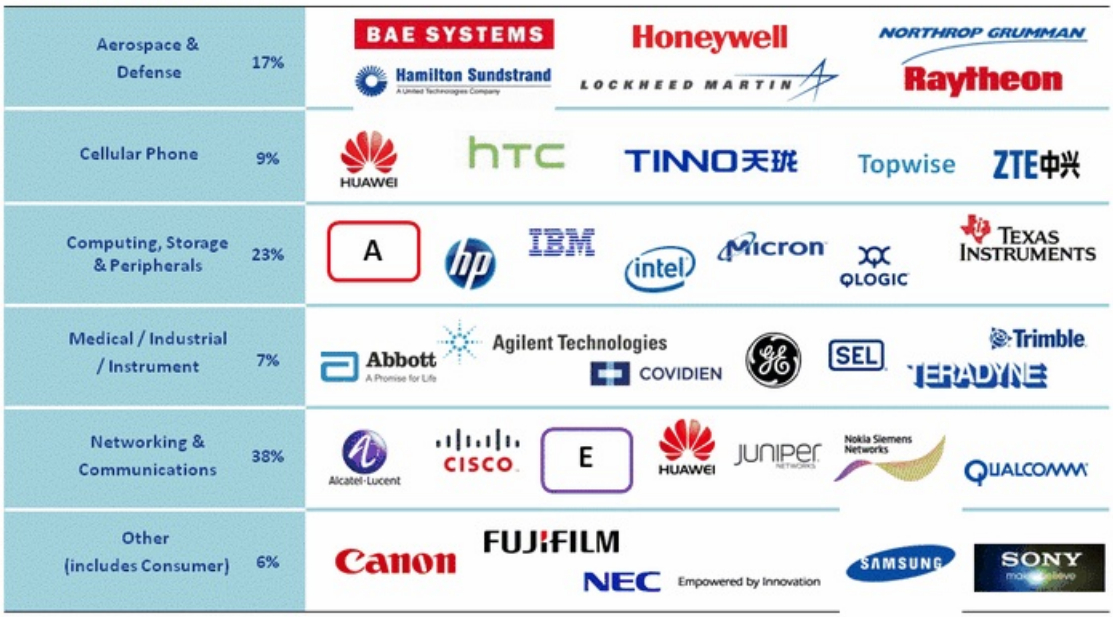
Diversified End Markets



2Q 2011 Sales

Diversified End Market & Customer Base

Selected Customers by End Market



Q2 2011 Sales

END MARKET REVIEW

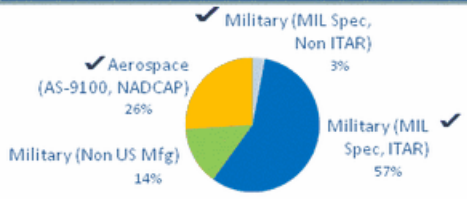
Aerospace & Defense

Available Market & CAGR:

- 2010 PCB TAM: $1.7 billion
  % of total PCB demand: 3.2%
- 2010 Target Market $1.4 billion
  2010 – 2015 CAGR: 4.1%

Total World PCB Market 2010: $52.5 billion - Prismark – August 2011

2010 Mil. / Aero. PCB Markets



Total: $1.7B

Prismark – August 2011

TTM Market Facts:

- Active OEM customers: 124
- Avg. customer volume: $1.9 million
- 2010 Sales: 236.9 million
  % of sales 17%
- 2011 1H Sales: $116.2 million
  % of sales 16%

Market Factors:

DEFENSE

Source: Boeing Current Market Outlook, Feb 2011

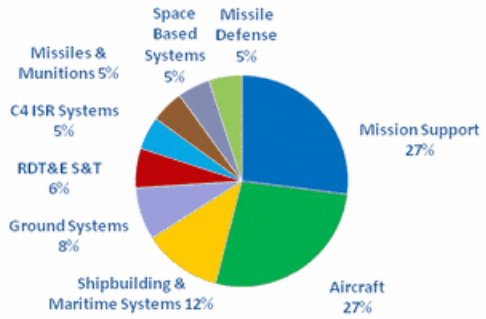
- DOD budget uncertainty
- Force modernization continues
- Foreign Military Sales (FMS) growth
- Program alignment essential

COMMERCIAL AEROSPACE

- 2011-2030 growth outlook
  - Airline traffic: 5.1% CAGR
  - Cargo traffic: 5.6% CAGR
- Fleet growth & replacement
  - 33,500 new aircraft forecast
- After market fleet upgrades

Aerospace & Defense – Industry Considerations

FY 2012 Strategic Modernization Budget



Total = $204 billion

Source: FY 2012 PRCP (DoD) investment categorization

N. America Military/Aerospace PCB Market Share

Rank	Maker	2010	%
1	TTM Technologies	$236	22%
2	DDI	$90	9%
3	Pioneer Circuits	$38	4%
4	Viasystems	$35	3%
5	Sanmina-SCI	$33	3%
Top 5 Total		**$432**	**41%**
Total N. America Military PCB Market		**$1,054**	**100%**

NT Information – August 2011

- Despite budget uncertainty, US DoD requires modernization
- TTM enjoys strong historical leadership position in most substantial markets
  - Significant barriers to market entry
  - Supply base fragmented, small & fragile
- TTM customer relations & global footprint supports future CA globalization

TTM Products & Select A&D Applications

- Conventional PCB
- Backplane PCB
- HDI PCB
- Specialty Materials PCB
- RF PCB
- Thermal Management PCB
- Flex & Rigid-Flex
- Large Format PCB & Rigid-Flex
- Flex & Rigid-Flex Assembly
- Backplane Assembly
- Chassis Assembly
- System Integration
- Specialty Assembly Products

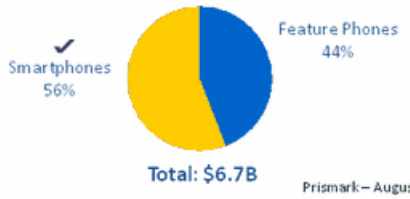
Cellular Phone

Available Market & CAGR:

- 2010 PCB TAM: $6.7 billion
  % of total PCB demand 12.8%
- 2010 Target Market: $3.8 billion
  2010 – 2015 CAGR: 12.3%

Total World PCB Market 2010: $52.5 billion - Prismark – August 2011

2010 Cellular Phone PCB Market



Total: $6.7B

Prismark – August 2011

TTM Market Facts:

- Active OEM customers: 23
- Average customer revenue: $6.9 million
- 2010 Sales: $158.3 million
  % of sales 12%
- 2011 1H Sales: $65.3 million
  % of sales 9%

Market Factors:

- Smartphone sales increasing dramatically at the expense of feature phones
- Strong growth outlook for 3G and 4G smartphone products fueled by ever-increasing demand for content
- By 2020 smartphones will represent 80% of all mobile devices, up from 27% in 2010
  Source: Jefferies, Mobility 2020
- Mobile data is expected to grow over 2500% by 2015 from 2010 levels, the highest rate of all types of IP traffic
  Source: Cisco VNI Mobile, 2011

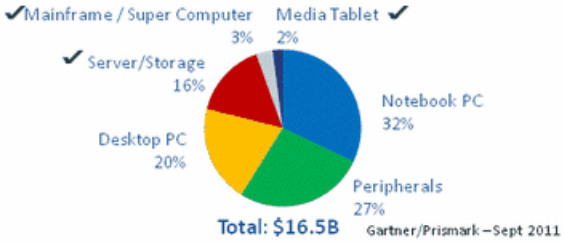
Computing

Available Market & CAGR:

- 2010 PCB TAM: $16.5 billion
  % of total PCB demand 31.4%
- 2010 Target Market : $3.5 billion
  2010 – 2015 CAGR: 12.2%
  2010 – 2015 Tablet CAGR: 44.1%

Total World PCB Market 2010: $52.5 billion - Prismark – August 2011

2010 Computing PCB Market



Gartner/Prismark – Sept 2011

TTM Market Facts:

- Active OEM customers: 162
- Avg. customer revenue: $1.9 million
- 2010 Sales: $307.1 million
  % of sales 22%
- 2011 1H Sales: $176.9 million
  % of sales 25%

Market Factors:

- Explosive growth in mobile devices; Increasing quality of content; Immediacy of content movement; storage & availability of content.
- Tablet revenue expected to grow from $5.9 billion in 2010 to $82.5 billion in 2015
  Source: Gartner, June 2011
- Increasing demand for cloud services will make cloud infrastructure products the fastest IT spend growth segment
  Source: Gartner, June 2011

Medical / Instrument / Industrial

Available Market & CAGR

- 2010 PCB TAM: $3.6 billion
  % of total PCB demand 6.9%
- 2010 Target Market : $2.0 billion*
  2010 – 2015 CAGR: 5 - 7%

* Excludes certain medical and low technology industrial and instruments
Total World PCB Market 2010: $52.5 billion - Prismark – August 2011

2010 MII PCB Market

Total: $3.6B

Prismark – Sept 2011

TTM Market Facts:

- Active OEM customers: 255
- Avg. customer revenue: $456 thousand
- 2010 sales: $116.4 million
  % of sales 8%
- 2011 1H sales: $55.3 million
  % of sales 8%

Market Factors:

- MII customers typically High Mix / Low Volume (HMLV)
- Medical - Product innovation & automation of medical records
- Industrial - Industrial automation & utility infrastructure management
- Instrumentation - Strong demand for flash memory and wireless chip sets support long term growth prospects for makers of semiconductor capital equipment

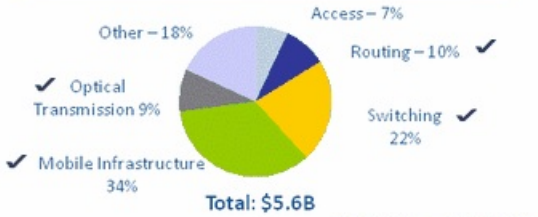
Networking & Communications

Available Market & CAGR:

- 2010 PCB TAM: $5.8 billion
  % of total PCB demand 11.0%
- 2010 Target Market : $4.2 billion
  2010 – 2015 CAGR: 5.9%

Total World PCB Market 2010: $52.5 billion - Prismark – August 2011

2010 Networking & Comm. PCB Mkt.



Dell'Oro/Prismark – Sept 2011

TTM Market Facts:

- Active OEM customers: 195
- Avg. customer revenue: $2.5 million
- 2010 sales: $481.4 million
  % of sales 35%
- 2011 1H sales: $257.1 million
  % of sales 36%

Market Factors:

- World's data is more than doubling every 2 years
  - Mobile device growth
  - Social networking
  - Massive content movement
- Increasing IP traffic fuels Service Provider spending on networking & communication hardware
  - IDC projects $125 billion CSP equipment spend by 2015

IDC – May & July 2011

TTM Products & Selected Commercial Applications

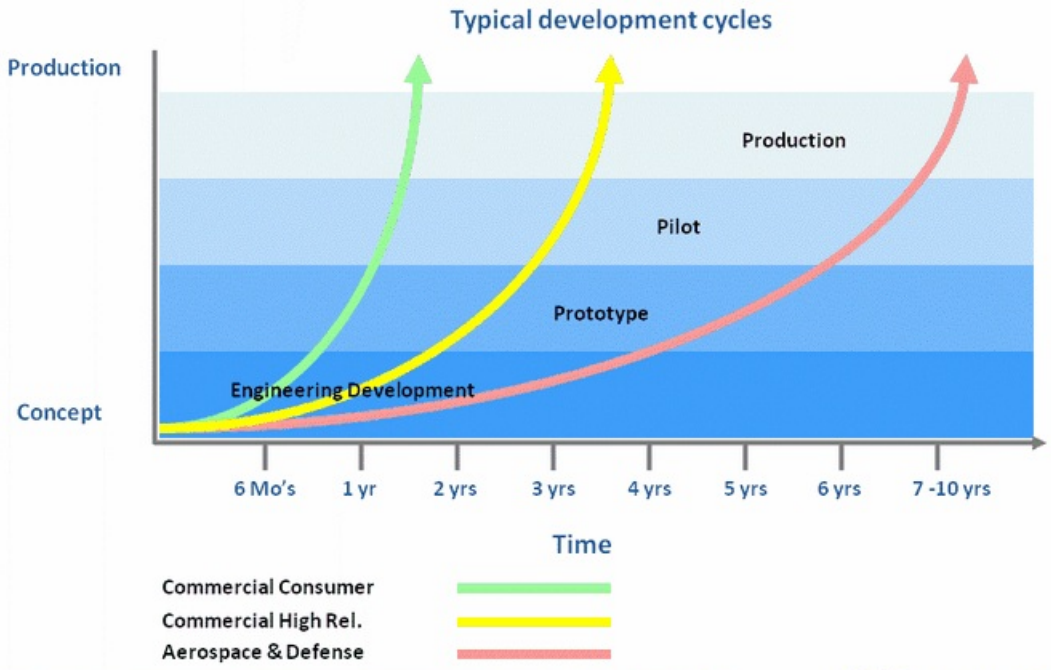
- Conventional PCB
- Backplane PCB
- HDI & Advanced HDI PCB
- High tech laminate PCB
- Rigid-Flex
- Flex
- Flex Assembly
- Backplane Assembly
- Chassis Assembly







Business Development Cycles Vary by Customer Type



Summary – Key Messages

- Large, multidimensional global sales force drives worldwide revenue growth
- Customer & end market diversification creates business balance
- Strategic customer collaboration drives successful business investment results
- Focus on growth customers and markets + higher technology product solutions = TTM superior industry performance

PCB Technology Trends and Focus

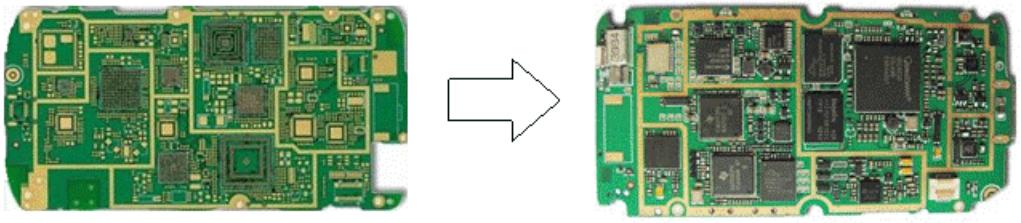
Global Presence | Local Knowledge

Shane Whiteside

September 28, 2011

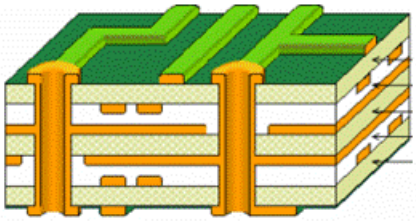
The Role of the Printed Circuit Board

- What is a PCB?
  - A PCB is a customized component that provides interconnections between other active & passive components and power & ground in an electronic assembly
  - PCB's are customized for each electronic device, appliance, or system
  - There are no "off the shelf" PCBs



PCB Technology Parameters

- Line width & space
- Number of Layers
- Hole size
- Aspect ratio
- Material type
- Embedded components
- Signal integrity
- High Density Interconnect

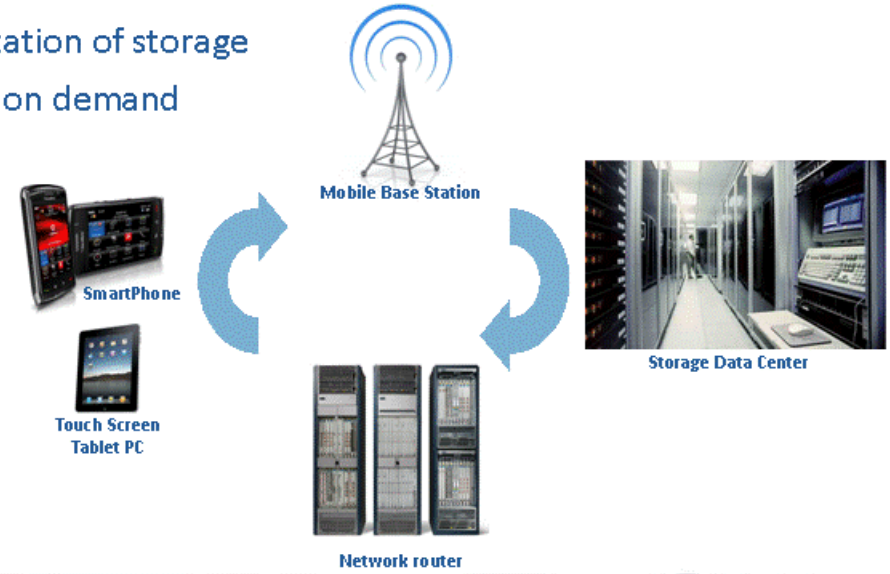


The PCB is custom-designed by OEMs for unique end market products, using selected manufacturers with capable technologies. TTM provides an industry-leading portfolio of advanced manufacturing capabilities.

TTM's Strategy is to be a leader in the markets we serve through superior technology, execution, and service to our Customers

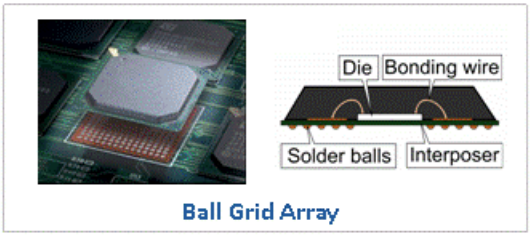
Factors Driving Printed Circuit Board Technology

- Connected society
- Richer content
- Centralization of storage
- Delivery on demand



Higher Functionality, Smaller Size

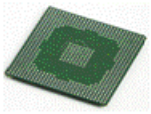
- Smaller Products that deliver more . . .
  - Computing power
  - Connectivity
  - Battery life

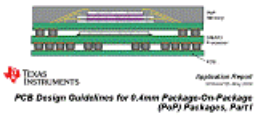


Ball Grid Array

- Require PCB's that provide
  - Higher density
  - Smaller features
  - Flexible routing through use of HDI

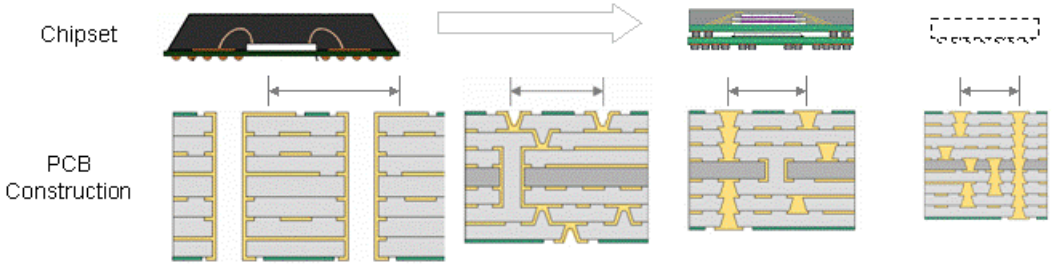
System on Chip





High Density Interconnect Trends

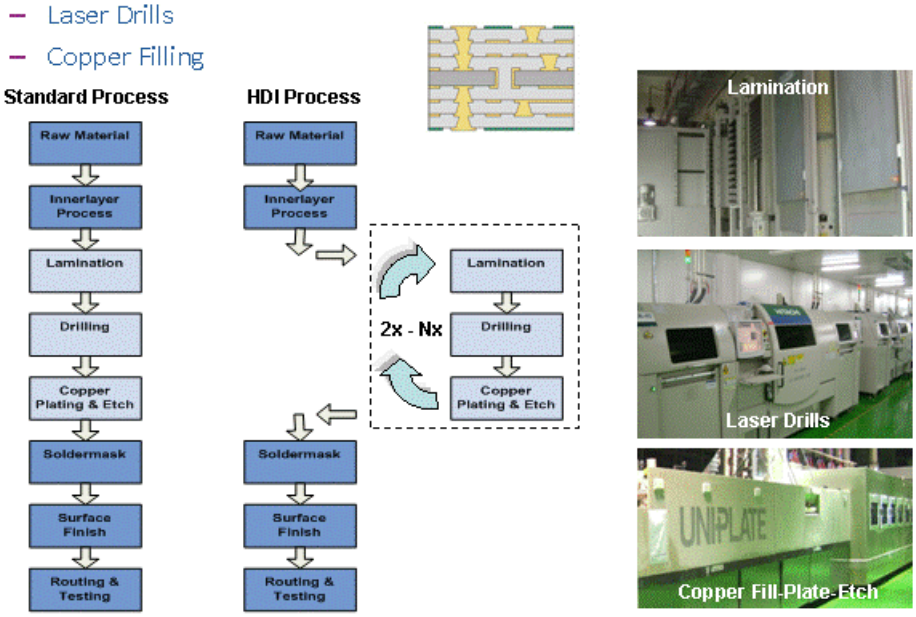
- Migration from through-hole connections to HDI PCB
- Higher density & quantity of I/O's at the Chipset interface drives the need for HDI routing in the PCB



Structure	Conventional	2+n+2 (6L)	3+n+3 (8L)	4+n+4, any-layer (10L)
Line & Space	100-125 µm	100-75 µm	100-75 µm	50-40 µm
Hole size	250-300 µm	120-100 µm	100-75 µm	75-50 µm
PCB Thickness	1.5 mm	1,0-0,9 mm	1,0-0,8mm	0,7-0,6 mm

Manufacturing PCB's with HDI

- HDI requires specialized equipment and processes
  - Laser Drills
  - Copper Filling



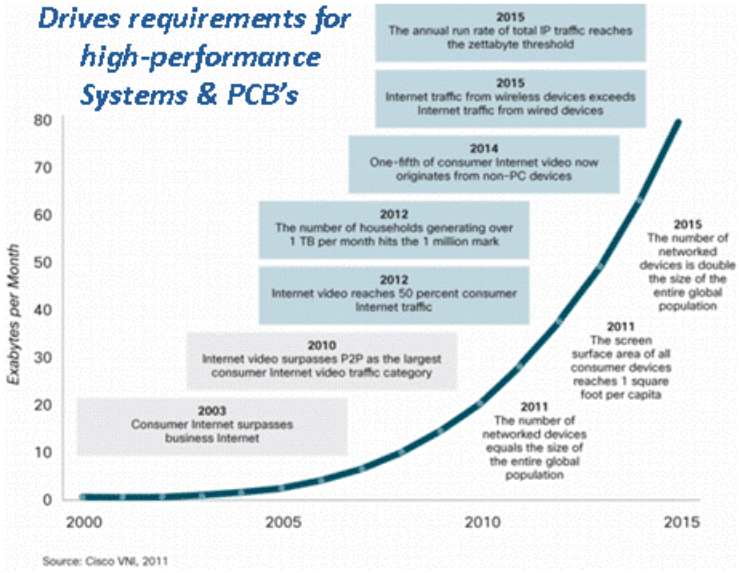
Connectivity of Devices requires Network Capacity

- More data volume
  - Web traffic
  - Gaming
  - Video
- Growth in devices
  - More Users
  - More devices per User

➡ Exponential expansion in required capacity

Network Traffic Expansion

- Mobile network traffic expected to double every 18 months
- Server I/O traffic doubles in 24 mos



PCB Applications in Communication

- Advanced technology PCB's are used in
  - Network routers & switches
  - Network servers and storage
  - 3G & 4G base stations

- Technology trends in Networking & Computing PCB's
  - Increasing layer count
  - Smaller holes & higher aspect ratios
  - Next generation low-loss materials
  - Tighter manufacturing tolerances
  - Signal performance optimization

PCB Applications in Communication

- Specialized Capabilities
  - Tight tolerance registration of layers – holes - features
  - Large size format
  - Next-generation materials
    - Manufacturing consistency
    - Performance characterization
    - Reliability performance
  - Signal performance optimization
  - Small batch production

R&D efforts to address future PCB Technologies

Reduced component pitch with finer feature sizes

→ **Projects to support:**

- Small Laser Via Technology --- Laser drilling
- mSAP³ Technology
- SAP³ Technology
- Small Laser Via Technology --- High A/R > 1
- High Aspect Ratio PTH < 20:1

More functions – for more challenging designs

→ **Projects to support:**

- Embedded Resistors and Capacitors
- Rigid-flex Technology
- Silver paste interconnection
- Any layer technology
- Ultra thin and stiffer materials
- 3D Embedded Device

Manufacturing Developments – Lead time and Cost

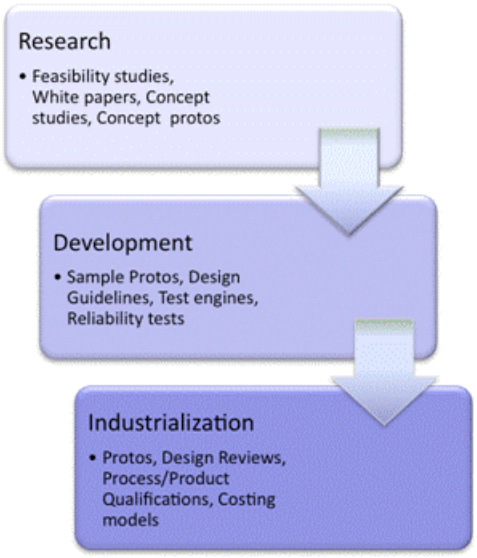
→ **Projects to support:**

- Carbon Technology
- Printable Electronics

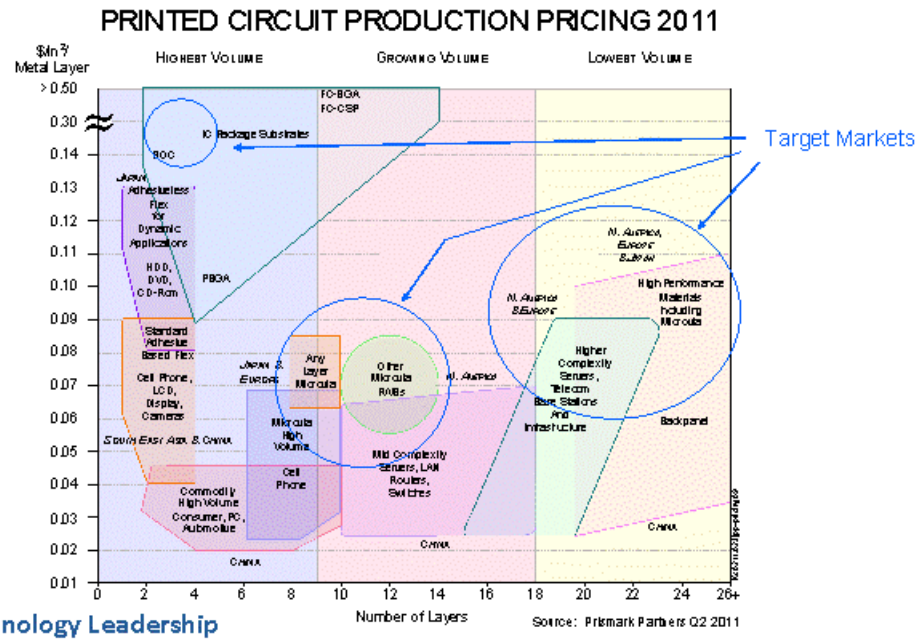
High frequency development

→ **Projects to support:**

- Board level optical interconnection
- Material Qualifications and Testing development



Market Leadership through Technology



- Technology Leadership
  - Narrows competitive landscape
  - Rewards successful performers

Summary

- TTM maintains market leadership through technology
- World-class factories, capabilities, and staff
- Engaged with leading OEM's
- Globally positioned
- Capacity to invest
- Expertise to execute

TTM Asia Pacific Growth Strategy

Global Presence | Local Knowledge

CANICE CHUNG

September 28, 2011

Agenda

- Asia Pacific Overview
- Asia Pacific Market Place & Competitive Landscape
- Asia Pacific Growth Drivers
- Capacity Review & Expansion Plan

ASIA PACIFIC OVERVIEW

Asia Pacific Overview

- 7 factories
- 14,000 employees
- About 2.65M sq. ft. capacity per month (annualized capacity of over 31.8 M sq. ft.)
- Advanced and high tech product strategies
- Ramp and volume capability

Plant Specialties in Asia Pacific

High Tech/Quick-Turn/High Mix
1. Hong Kong – OPCM

Volume Production
2. Dongguan – DMC
3. Dongguan – SYE
4. Guangzhou – GME
5. Shanghai – SME
6. Suzhou – MAS

Substrate
7. Shanghai - SMST

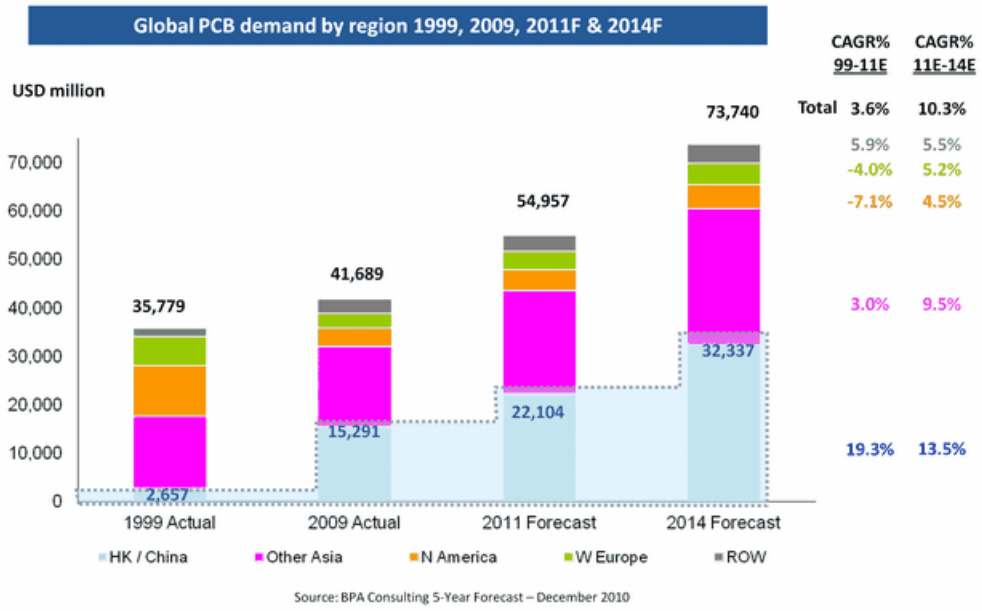
Location	Facility	Product Type	Specialty	Annual Capacity
1 Hong Kong	OPCM	✓ ✓ ✓	High mix, QTA & Commercial Aerospace	0.4M sq ft
2 Dongguan	DMC	✓ ✓	Embedded Components/ Advanced Technology / Heavy Copper	10.0M sq ft
3 Dongguan	SYE	✓ ✓	Specialty in High Speed Material/ Hybrid / Coin	5.3M sq ft
4 Guangzhou	GME	✓ ✓ ✓ ✓ ✓	Advanced HDI/ RF / Flex / Flex assembly/ COIN	6.5M sq ft*
5 Shanghai	SME	✓ ✓ ✓ ✓	Advanced HDI/ RF	5.0M sq ft
6 Shanghai	SMST-SP	✓ ✓ ✓	IC Substrate	1.0M sq ft
7 Suzhou	MAS	✓ ✓ ✓	Advanced HDI for Handheld Devices	3.6M sq ft

Note*: 0.6M sq ft - Flex & Rigid Flex products

Conventional | HDI | Advanced HDI | IC Substrate | FPC / FPCA | Rigid Flex

ASIA MARKET PLACE & COMPETITOR LANDSCAPE

Migration of demand to China



Source: BPA Consulting 5-Year Forecast – December 2010

Competitor Landscape

2010 Ranking		Substrate	Technology (Substrate/ 2+ or above)	Volume (Cost, 2-8L)	Niche (Flex)	End Markets Served		Plant Locations
1.	Unimicron	✓	✓	✓	✓	A. Cellular Phone/ Mobile Devices B. Computer/ Storage/ Peripherals C. Communication/ Networking	D. Consumer Electronics/ Game Console E. Automotive F. Business/ Office equipment	Taiwan, Suzhou, Kunshan, Shenzhen
2.	Ibiden	✓	✓			A. Cellular Phone/ Mobile Devices B. Computer/ Storage/ Peripherals	C. Industrial/ Medical/ Instrumentation and control D. Consumer Electronics/ Game Console	Japan, Philippines, Beijing, Penang
3.	Nippon Mektron		✓		✓	A. Cellular Phone/ Mobile Devices B. Computer/ Storage/ Peripherals C. Industrial/ Medical/ Instrumentation and control	D. Communication/ Networking E. Consumer Electronics/ Game Console F. Automotive	Japan, Zhuhai, Suzhou, Thailand
4.	Tripod	✓	✓	✓		A. Cellular Phone/ Mobile Devices B. Computer/ Storage/ Peripherals C. Communication/ Networking	D. Consumer Electronics/ Game Console E. Automotive	Taiwan, Wuxi
5.	TTM	✓	✓		✓	A. Cellular Phone/ Mobile Devices B. Computer/ Storage/ Peripherals C. Industrial/ Medical/ Instrumentation and control D. Communication/ Networking	E. Consumer Electronics/ Game Console F. Automotive G. Aerospace/ Defense	Hong Kong, Dongguan, Guangzhou, Shanghai, Suzhou, US
6.	SEMCO	✓		✓		A. Cellular Phone/ Mobile Devices B. Computer/ Storage/ Peripherals C. Consumer Electronics/ Game Console	D. Automotive E. Aerospace/ Defense	Kunshan
7.	Nanya PCB	✓	✓	✓		A. Cellular Phone/ Mobile Devices B. Computer/ Storage/ Peripherals	C. Consumer Electronics/ Game Console D. Automotive	Kunshan
8.	Foxconn			✓		A. Cellular Phone/ Mobile Devices B. Computer/ Storage/ Peripherals C. Communication/ Networking	D. Consumer Electronics/ Game Console E. Business/ Office equipment	Taiwan, Shenzhen, YanTai, Huai An, Yin Kou, Qin Huang Dao
9.	Hannstar Board			✓		A. Cellular Phone/ Mobile Devices B. Computer/ Storage/ Peripherals C. Communication/ Networking	D. Consumer Electronics/ Game Console E. Automotive	Taiwan, Jiangsu
10.	KB PCB Group			✓		A. Cellular Phone/ Mobile Devices B. Industrial/ Medical/ Instrumentation and control	C. Consumer Electronics/ Game Console D. Aerospace/ Defense	Hong Kong, Guangzhou, Kaiping, Nanjing, Wuxi, Thailand, Huiyang, Dongguan, Fogang

2010 Company Ranking in China

Top 5 China PCB Makers

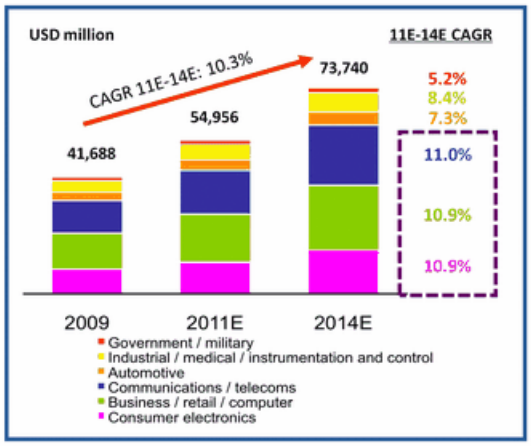
Rank	Company	Revenue est. US$ M
1	Tripod	$1,208
2	Foxconn	$1,150
3	Kingboard	$1,122
4	Hannstar	$1,078
5	TTM Technologies (Asia Pacific only)	$792

NT Information June 2011

Represents approximately 25% of total China PCB output

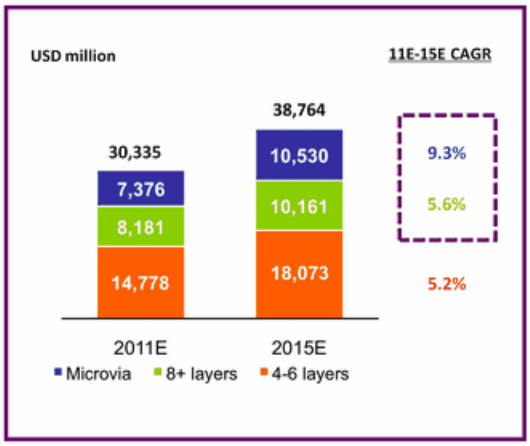
Fastest Growing Segments/ Product Types

Growth of world PCB market by application (11E-14E)



Source: BPA Consulting 5-Year Sectoral Forecast – Feb 2011

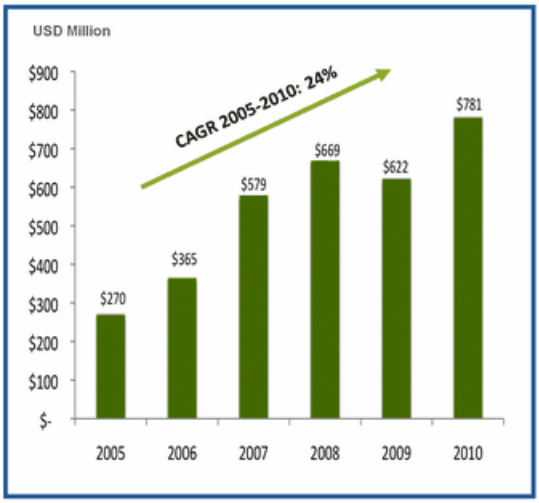
Migration towards high-end PCBs



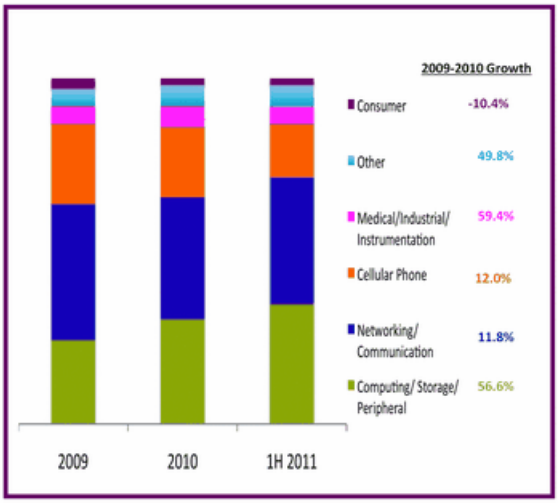
Source: Prismark 2Q Aug 2011

TTM AP Revenue Trend

Historical Pro Forma Revenue Trend



Market Segments of Asia Pacific Sales



Target growing end-markets

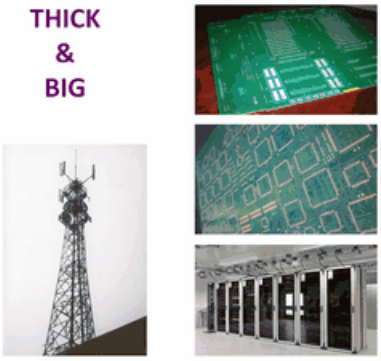
ASIA PACIFIC GROWTH DRIVERS

Product Strategy

THIN & LIGHT

- Advanced HDI PCBs & IC Substrates
- Fine line product applications Eg. handsets, high-end consumer products, smartphones, touch screen tablet PCs

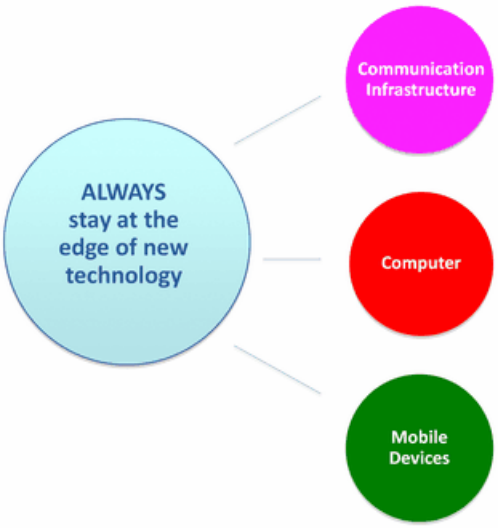
THICK & BIG



- Advanced Multi-layer & backplane PCBs
- Complex design for high speed applications
- Backplanes, base stations

Notes: 1 - 8L (3+ HDI), 2 - 10L (4+ Any Layer)

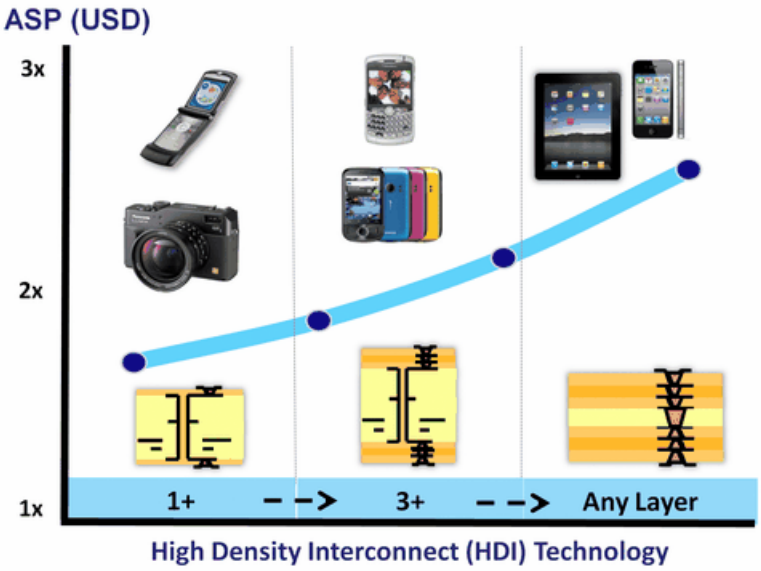
TTM AP Growth Drivers



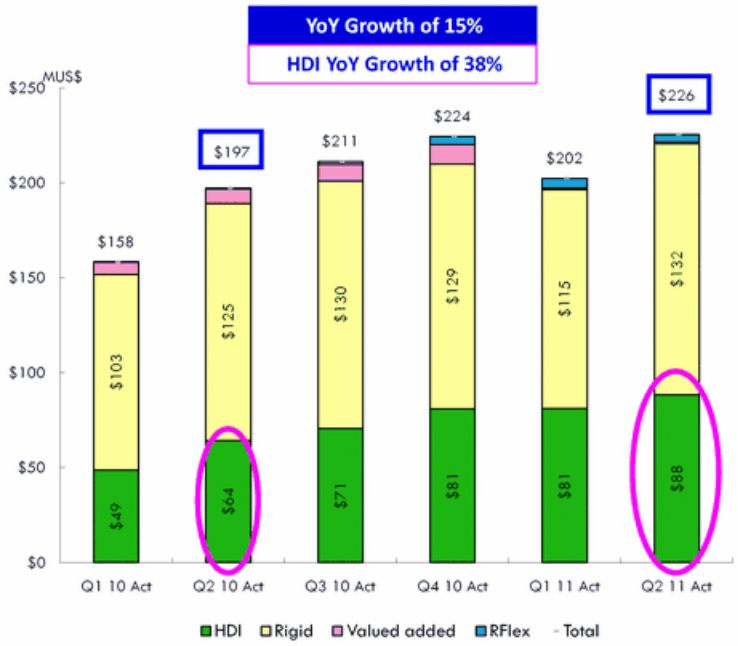
Revolutionary Growth Drivers for
Higher Speed & Wider Bandwidth

Early 1980s	Early 1990s	Early 2000s	2009	Future
1G-2G	2.5G	3G	4G	
Modem PC	Notebook/ Tablet PC	Touch screen Tablet		
Servers/ Storage		Clouds		
Analog Phones	Feature Phones	Smartphones		Mobile/ Media Devices

Technology & ASP



Asia Pacific Revenue Trend



- Increased demand for advanced HDI applications due to the launch of touchpad tablets and smartphones
- Continued demand for increased bandwidth

CAPACITY REVIEW & FUTURE EXPANSION PLAN

Annualized Capacity

Annualized Capacity[1] (as of 31 December)			
Factory	2010	2011	2012
	Million square feet		
OPCM (Hong Kong)	0.5	0.4	0.4
SYE (Dongguan)	5.3	5.3	5.3
DMC (Dongguan)	10.0	10.0	10.0
SME (Shanghai)	5.0	5.0	6.0
SMST (Shanghai)	1.0	1.0	1.0
GME (Guangzhou)	5.4	5.9	6.7
GME Flex (Guangzhou)	0.3	0.6	0.9
MAS (Suzhou)	3.6	3.6	3.6
RIGID PCB TOTAL	30.7	31.2	33.5
FLEX PCB TOTAL	0.3	0.6	0.9
TOTAL PCB	31.0	31.8	34.4

Note: 1 - Equals to available monthly capacity multiplied by twelve for the period stated.

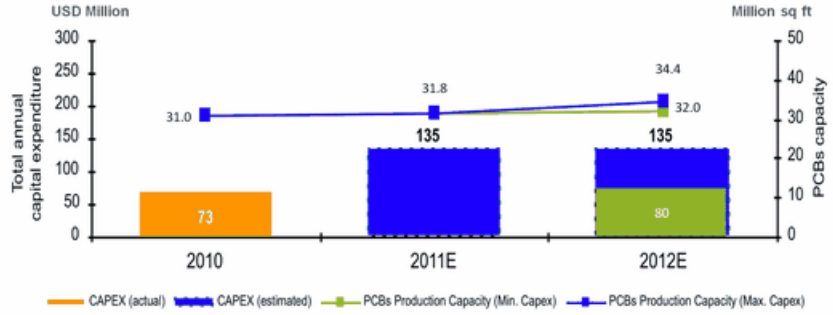
Plant technology focus & specialization by colors:	2012
QTA	0.4M sq ft
Conventional High Layer Count	15.3M sq ft
HDI (up to any layer)	16.3M sq ft
IC Substrates	1.0M sq ft
Flex and Rigid Flex	0.9M sq ft

- Focus on very high layer PCB & advanced HDI
- Target to grow 50% through value-add on ASP improvement & 50% by volume capacity expansion

Capex Planning

Facility	Location	Products	Expanded Capacity	Target Completion
DMC	Dongguan	Inner Layer Capability	NA	Q3, 2012
GME	Guangzhou	Advanced HDI, Conventional, Flex & Rigid-flex	Rigid PCB – 1.6 M sq.ft	Q3, 2012
			Flex PCB – 0.3 M sq.ft	
SME	Shanghai	Advanced HDI & Rigid Flex	Rigid & Rigid Flex PCB 1 M sq.ft.	Q4, 2012

Historical, estimated CAPEX and PCB, Substrates & Flex production capacity



Recap on Asia's Initiatives

Advanced Technologies Focus

- R&D for NPI
  - Understand industry and customers' product roadmaps and prepare our capabilities for the industries
- Launch & Ramp
  - ALWAYS stay on the edge of new & advanced technologies and ride on new product ramps

THANK YOU!

Financial Performance and Objectives

Global Presence | Local Knowledge

Steve Richards

September 28, 2011

Adjusted Income Statement – Q2 YTD Actual*

$ millions (except where noted)	Asia Pacific*	North America	Total*
Revenue	**$424.4**	**$284.5**	**$708.9**
Gross Profit	**99.9** 23.5%	**59.4** 20.9%	**159.3** 22.5%
Operating Income	**56.2** 13.2%	**29.1** 10.2%	**85.3** 12.0%
TTM Net Income	**38.0** 9.0%	**14.8** 5.2%	**52.8** 7.4%
GAAP Diluted EPS $ per share	**0.46**	**0.18**	**0.64**
Non-GAAP EPS $ per diluted share	**0.55**	**0.25**	**0.80**
EBITDA	**92.5** 21.8%	**38.2** 13.4%	**130.7** 18.4%

* Excludes $48.1 million impairment charge

Target Model

($ in millions, except EPS)	2011 Q1	2011 Q2*	2011 Q3 Est.	Target Model
Revenue	$342.8	$366.1	$365 - $385	10% - 12% Annual Growth
Gross Profit	$81.9	$77.3	$74 - $84	
Gross Margin	23.9%	21.1%	20% - 22%	23%
Operating Income	$45.7	$39.6	$36 - $45	
Operating Margin	13.3%	10.8%	10% - 12%	13%
GAAP Diluted EPS	$0.33	$0.31	$0.24 - $0.33	
Non-GAAP Diluted EPS	$0.40	$0.40	$0.32 - $0.41	
Operating Cash Flow	$37.1	$67.8		
Free Cash Flow	$10.6	$23.7		

* Excludes $48.1 million impairment charge

Competitive Benchmarking

	Ibiden	TTM	DDI	Tripod	Viasystems	Unimicron	Nanya PCB
GM %	25.5%	22.5%	21.6%	20.7%	19.0%	15.9%	13.6%
OM %	8.0%	12.0%	8.2%	12.3%	5.2%	9.4%	8.9%

Note: TTM operating margin excludes impact of $48.1 million impairment charge.

Balance Sheet Highlights

($ in millions)	December 31, 2010	June 27, 2011
Assets		
Cash and Cash Equivalents	$216.1	$235.9
Accounts and Notes Receivable, Net	287.7	294.6
Inventories	135.4	141.2
Property, Plant and Equipment, Net	740.6	736.5
Goodwill	197.8	197.7
Definite-Lived Intangibles, Net	97.9	89.2
All Other Assets	86.5	91.9
Total Assets	$1,762.0	$1,787.0
Liabilities and Equity		
ST Debt, Including Current Portion of LT Debt	67.1	123.2
Accounts Payable, Including Due to Related Parties	205.0	214.5
Convertible Senior Notes, Net	145.3	148.2
Long-Term Debt, Less Current Portion	313.0	255.8
All Other Liabilities	198.7	177.8
Total Liabilities	929.1	919.5
Total Equity	832.9	867.5
Total Liabilities and Equity	$1,762.0	$1,787.0

Cash Flow

($ in millions)	2010	YTD June 27, 2011
Net Income	$79.9	$8.8
Depreciation of Property, Plant and Equipment	48.7	32.5
Amortization of Definite-Lived Intangible Assets	13.8	8.5
Deferred Income Taxes	15.2	10.2
Stock-Based Compensation	6.9	3.9
Impairment of Long-Lived Assets	0.8	48.1
Other Operating Activities	7.5	3.1
Working Capital Changes	(47.0)	(10.2)
Cash Flow from Operations	125.8	104.9
Net Capital Expenditures	(59.9)	(70.6)
Other Investing Activities	92.9	0.0
Cash Flow from Investing Activities	33.0	(70.6)
Repayment of Borrowings, Net of Proceeds	(38.0)	(32.1)
Other Financing Activities	2.6	18.5
Cash Flow from Financing Activities	(35.4)	(13.6)
Free Cash Flow	$65.9	$34.3

TTM Key Statistics

	FY 09	FY 10	1H 11
ROIC	9.5%	11.3%	13.6%
ROA	3.9%	6.0%	6.1%
ROE	6.6%	12.4%	12.4%
Adjusted EBITDA Margin*	9.4%	16.5%	18.4%

* EBITDA adds back impairment charges

Working Capital Efficiency

	2009	2010	1Q11	2Q11
A/R Days	63.2	72.1	73.6	72.9
Inventory Days	49.1	46.2	46.7	45.0
A/P Days	49.5	89.1	93.5	88.9
Cash Conversion Cycle	62.8	29.2	26.8	29.0

Cash Flow Planning

($ in millions)

Cash Performance	2010 1H	2010 2H	2011 1H
Operating Cash Flow	$19.8	$106.1	$104.9
Net Capital Expenditures	14.8	45.1	70.6
Free Cash Flow	5.0	61.0	34.3
Debt Payments - Net of Draws	-	38.0	32.1
Cash Flow - Net	5.0	23.0	2.2

Cash Requirements	2011 2H	2012 1H	2012 2H	2013 1H	2013 2H
Net Capital Expenditures	$64.4	$55.0	$55.0	$55.0	$55.0
Debt Payments	35.0	68.4	52.5	63.3	140.0
Total	99.4	123.4	107.5	118.3	195.0

Leverage and Gearing Ratios

($ in millions)

Leverage	2010 1H	2010 2H	2011 1H
Total Debt	$613.0	$555.4	$554.2
LTM EBITDA	191.8	249.7	265.0
Debt / LTM EBITDA	3.2	2.2	2.1

Gearing	TTM Asia Pacific		
	2010 1H	2010 2H	2011 1H
Total Borrowings (Gross)	$437.6	$380.1	$379.0
Less: Cash and Bank Balances	153.2	129.2	113.7
Consolidated Net Borrowings	284.4	250.9	265.3
Consolidated Tangible Net Worth	231.6	285.8	299.0
Consolidated Net Borrowings : TNW	1.23	0.88	0.89

Investment Highlights

- Market leader in advanced technology PCBs globally
- Strong track record of operating performance
- Emphasis on customer service with facilities tailored to meet customer needs now and in the future
- Focused on growth through organic opportunities as well as strategic acquisitions
- Healthy balance sheet and solid cash flow funding growth

Appendix

Reconciliations

($ in millions, except EPS)	2010	YTD June 27, 2011
Adjusted EBITDA Reconciliation:		
Net Income	$79.9	$8.8
Add Back Items:		
Income Tax Provision	28.7	19.8
Interest Expense	22.3	13.0
Depreciation Expense	48.7	32.5
Amortization of Intangibles	13.8	8.5
EBITDA	$193.4	$82.6
Add Back: Impairment of Long-lived Assets	$0.7	$48.1
Adjusted EBITDA	$194.1	$130.7
Non-GAAP EPS Reconciliation:		
Net Income Attributable to Stockholders	$71.5	$6.2
Add Back Items:		
Amortization of Intangibles	13.8	8.5
Stock-Based Compensation	6.9	3.9
Non-Cash Interest Expense	7.7	4.3
Impairment, Restructuring and Other Charges	17.8	48.1
Income Tax Effects	(12.2)	(4.8)
Non-GAAP net income attributable to stockholders	$105.5	$66.2
Non-GAAP earnings per diluted share attributable to stockholders	$1.49	$0.80
Diluted Shares	70,819	82,396